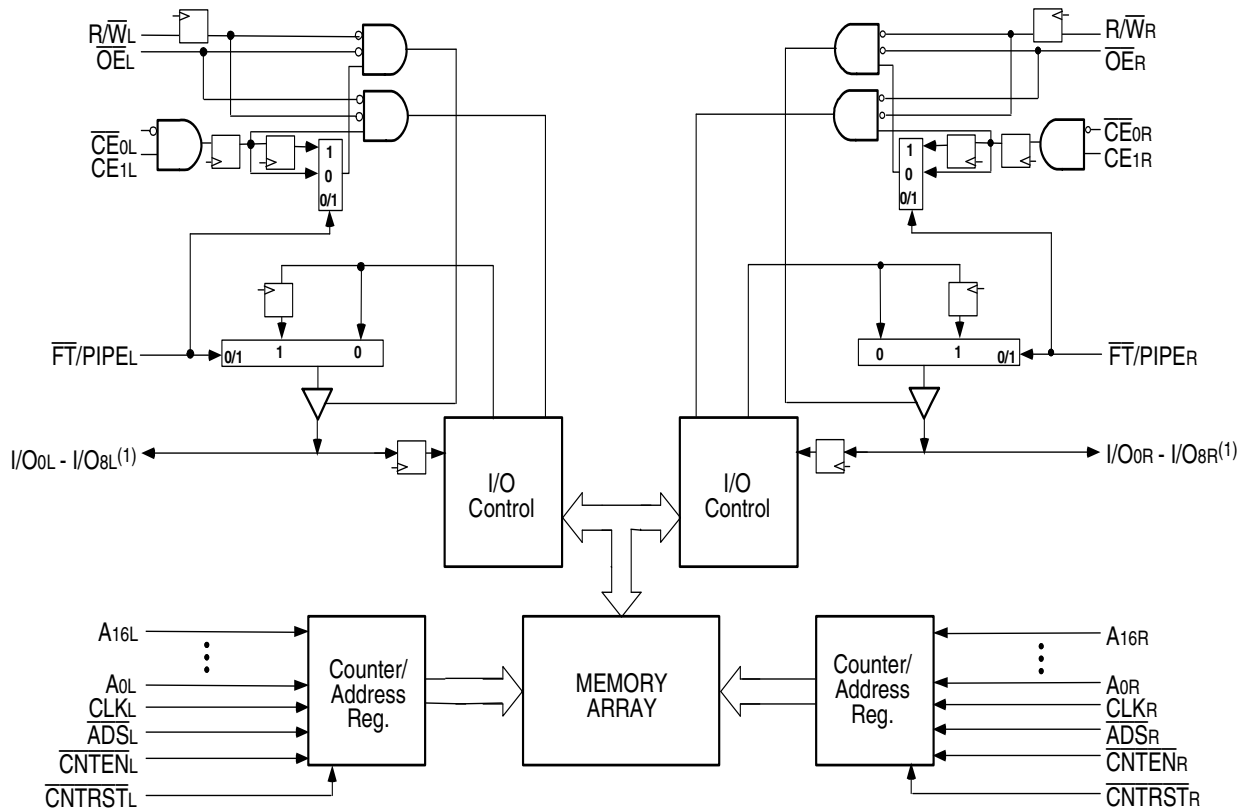


Features:

- ◆ True Dual-Ported memory cells which allow simultaneous access of the same memory location
- ◆ High-speed clock to data access
 - Commercial: 9ns (max.)
 - Industrial: 9ns (max.)
- ◆ Low-power operation
 - IDT70V9199/099L
 - Active: 500mW (typ.)
 - Standby: 1.5mW (typ.)
- ◆ Flow-Through or Pipelined output mode on either port via the $\overline{\text{FT}}/\text{PIPE}$ pins
- ◆ Dual chip enables allow for depth expansion without additional logic
- ◆ Counter enable and reset features
- ◆ Full synchronous operation on both ports
 - 4ns setup to clock and 1ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 9 ns clock to data out in the Pipelined output mode
 - Self-timed write allows fast cycle time
 - 15ns cycle time, 66 MHz operation in Pipelined output mode
- ◆ LVTTTL-compatible, single 3.3V ($\pm 0.3\text{V}$) power supply
- ◆ Industrial temperature range (-40°C to $+85^\circ\text{C}$) is available for selected speeds
- ◆ Available in a 100-pin Thin Quad Flatpack (TQFP)
- ◆ Green parts available, see ordering information

Functional Block Diagram



4859 drw 01

NOTE:

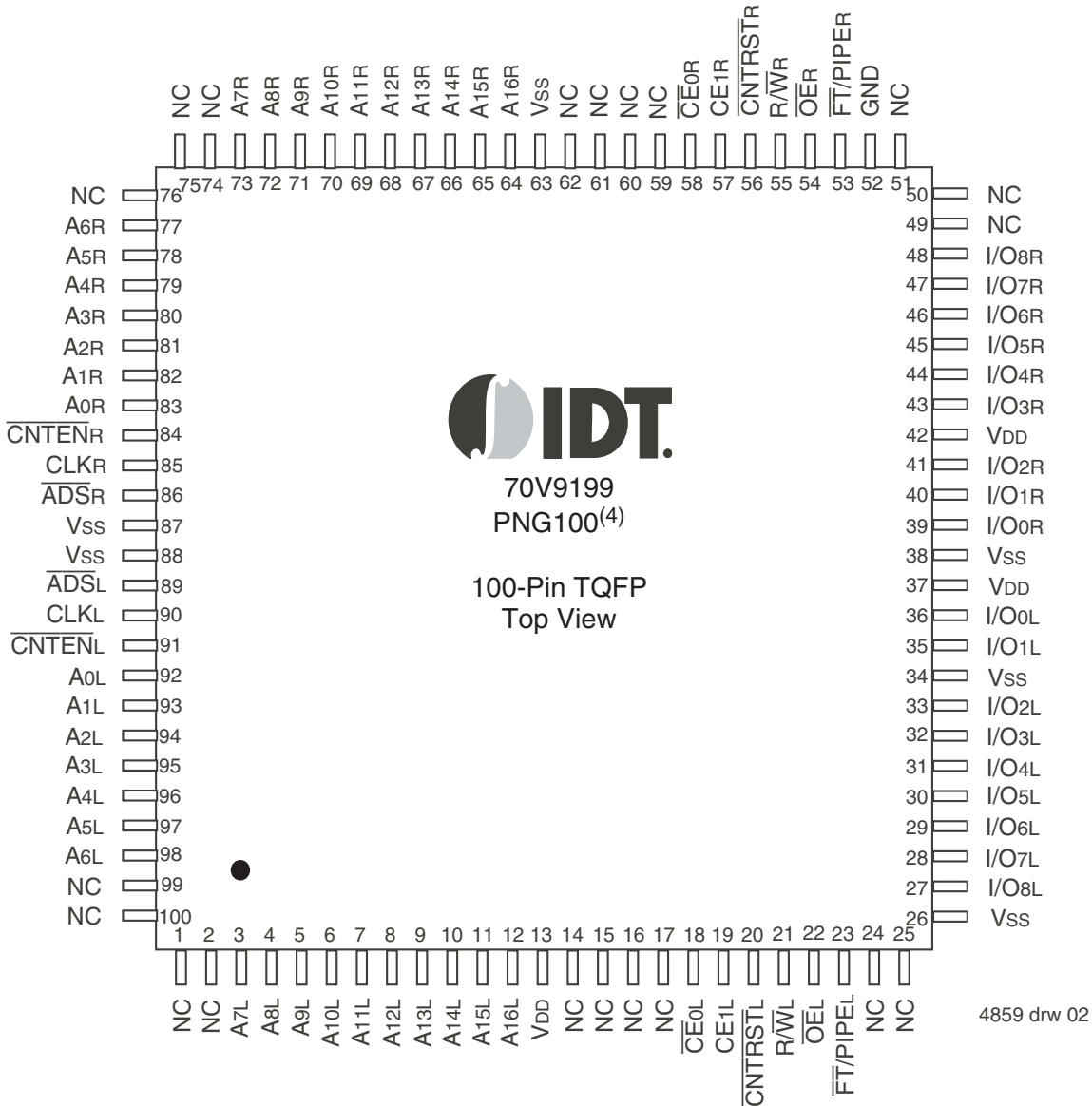
1. I/O_{0x} - I/O_{7x} for IDT70V9099.

Description:

The IDT70V9199/099 is a high-speed 128K x9/x8 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

With an input data register, the IDT70V9199/099 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{CE0}$ and $CE1$, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using CMOS high-performance technology, these devices typically operate on only 500mW of power.

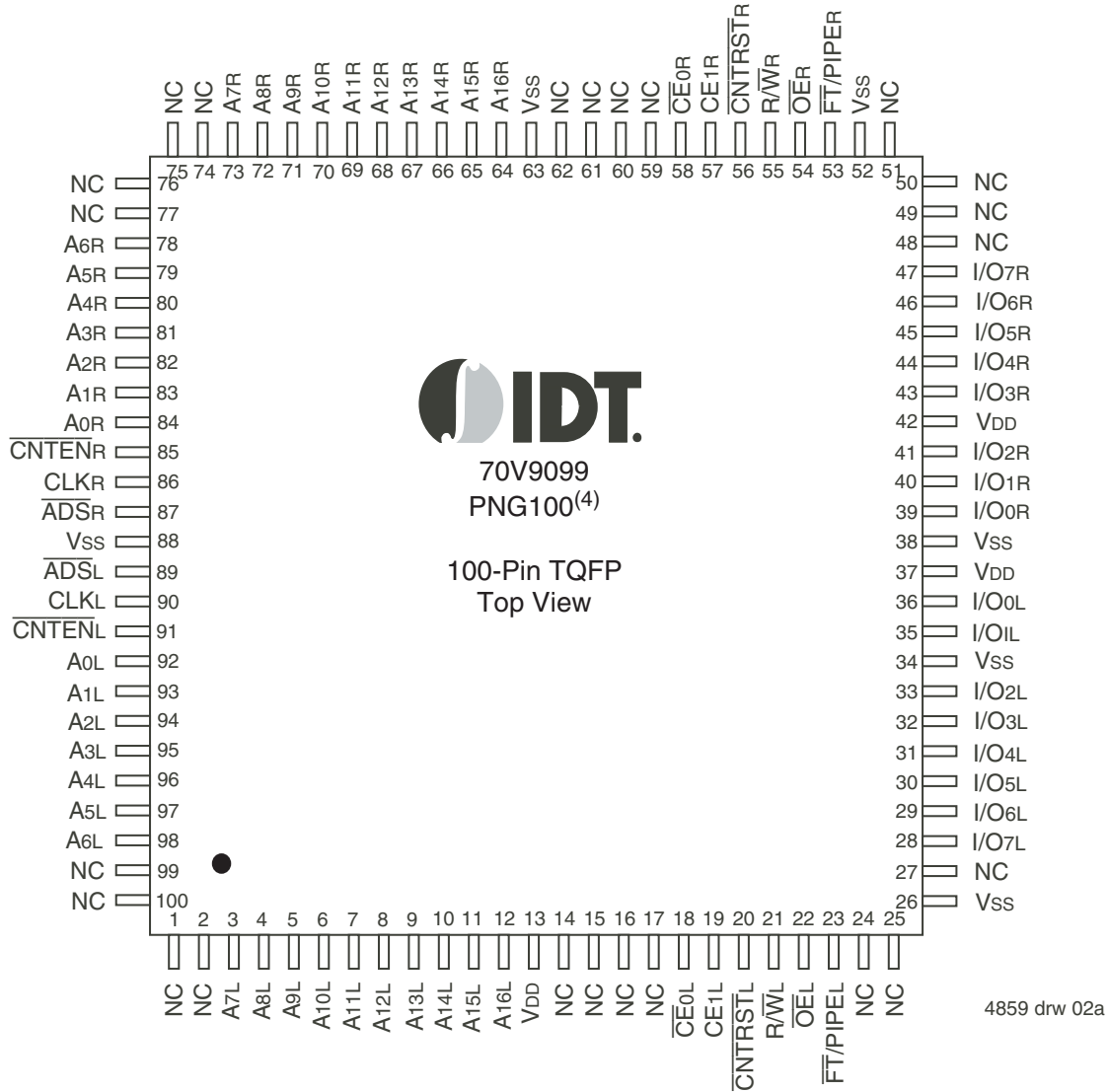
Pin Configuration^(1,2,3)



NOTES:

1. All VDD pins must be connected to power supply.
2. All VSS pins must be connected to ground supply.
3. Package body is approximately 14mm x 14mm x 1.4mm.
4. This package code is used to reference the package diagram.

Pin Configuration^(1,2,3)(con't.)



NOTES:

1. All V_{DD} pins must be connected to power supply.
2. All V_{SS} pins must be connected to ground.
3. Package body is approximately 14mm x 14mm x 1.4mm.
4. This package code is used to reference the package diagram.

Pin Names

| Left Port | Right Port | Names |
|------------------------------|------------------------------|-------------------------|
| \overline{CE}_{0L} , CE1L | \overline{CE}_{0R} , CE1R | Chip Enables |
| R/ \overline{W} L | R/ \overline{W} R | Read/Write Enable |
| \overline{OE} L | \overline{OE} R | Output Enable |
| A0L - A16L | A0R - A16R | Address |
| I/O0L - I/O8L ⁽¹⁾ | I/O0R - I/O8R ⁽¹⁾ | Data Input/Output |
| CLKL | CLKR | Clock |
| \overline{ADS} L | \overline{ADS} R | Address Strobe Enable |
| \overline{CNTEN} L | \overline{CNTEN} R | Counter Enable |
| \overline{CNRST} L | \overline{CNRST} R | Counter Reset |
| $\overline{FT/PIPE}$ L | $\overline{FT/PIPE}$ R | Flow-Through / Pipeline |
| VDD | | Power (3.3V) |
| VSS | | Ground (0V) |

NOTE:

1. I/O0x - I/O7x for IDT70V9099.

4859 tbl 01

Truth Table I—Read/Write and Enable Control^(1,2,3)

| \overline{OE} | CLK | \overline{CE}_0 | CE1 | R/ \overline{W} | I/O0-8 ⁽⁴⁾ | MODE |
|-----------------|-----|-------------------|-----|-------------------|-----------------------|-----------------------|
| X | ↑ | H | X | X | High-Z | Deselected—Power Down |
| X | ↑ | X | L | X | High-Z | Deselected—Power Down |
| X | ↑ | L | H | L | DATA _{IN} | Write |
| L | ↑ | L | H | H | DATA _{OUT} | Read |
| H | X | L | H | X | High-Z | Outputs Disabled |

4859 tbl 02

NOTES:

- "H" = V_{IH}, "L" = V_{IL}, "X" = Don't Care.
- \overline{ADS} , \overline{CNTEN} , \overline{CNRST} = X.
- \overline{OE} is an asynchronous input signal.
- I/O0 - I/O7 for IDT70V9099.

Truth Table II—Address Counter Control^(1,2)

| External Address | Previous Internal Address | Internal Address Used | CLK | \overline{ADS} | \overline{CNTEN} | \overline{CNRST} | I/O ⁽³⁾ | MODE |
|------------------|---------------------------|-----------------------|-----|------------------|--------------------|--------------------|-----------------------|---|
| X | X | 0 | ↑ | X | X | L ⁽⁴⁾ | D _{IO} (0) | Counter Reset to Address 0 |
| A _n | X | A _n | ↑ | L ⁽⁴⁾ | X | H | D _{IO} (n) | External Address Loaded into Counter |
| A _n | A _p | A _p | ↑ | H | H | H | D _{IO} (p) | External Address Blocked—Counter disabled (A _p reused) |
| X | A _p | A _p + 1 | ↑ | H | L ⁽⁵⁾ | H | D _{IO} (p+1) | Counter Enabled—Internal Address generation |

4859 tbl 03

NOTES:

- "H" = V_{IH}, "L" = V_{IL}, "X" = Don't Care.
- \overline{CE}_0 and \overline{OE} = V_{IL}; CE1 and R/ \overline{W} = V_{IH}.
- Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.
- \overline{ADS} and \overline{CNRST} are independent of all other signals including \overline{CE}_0 and CE1.
- The address counter advances if \overline{CNTEN} = V_{IL} on the rising edge of CLK, regardless of all other signals including \overline{CE}_0 and CE1.

Recommended Operating Temperature and Supply Voltage⁽¹⁾

| Grade | Ambient Temperature ⁽²⁾ | GND | VDD |
|------------|------------------------------------|-----|-------------|
| Commercial | 0°C to +70°C | 0V | 3.3V ± 0.3V |
| Industrial | -40°C to +85°C | 0V | 3.3V ± 0.3V |

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

4859 tbl 04

Recommended DC Operating Conditions

| Symbol | Parameter | Min. | Typ. | Max. | Unit |
|--------|--------------------|---------------------|------|-------------------------|------|
| VDD | Supply Voltage | 3.0 | 3.3 | 3.6 | V |
| VSS | Ground | 0 | 0 | 0 | V |
| VIH | Input High Voltage | 2.0 | — | VDD+0.3V ⁽²⁾ | V |
| VIL | Input Low Voltage | -0.3 ⁽¹⁾ | — | 0.8 | V |

NOTES:

- VIL ≥ -1.5V for pulse width less than 10 ns.
- VTERM must not exceed VDD +0.3V.

4859 tbl 05

Absolute Maximum Ratings⁽¹⁾

| Symbol | Rating | Commercial & Industrial | Unit |
|----------------------|--------------------------------------|-------------------------|------|
| VTERM ⁽²⁾ | Terminal Voltage with Respect to GND | -0.5 to +4.6 | V |
| TBIAS ⁽³⁾ | Temperature Under Bias | -55 to +125 | °C |
| TSTG | Storage Temperature | -65 to +150 | °C |
| TJN | Junction Temperature | +150 | °C |
| IOUT | DC Output Current | 50 | mA |

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VTERM must not exceed VDD +0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to ≤ 20mA for the period of VTERM ≥ VDD + 0.3V.
- Ambient Temperature Under DC Bias. No AC Conditions. Chip deselect.

4859 tbl 06

Capacitance⁽¹⁾

(TA = +25°C, f = 1.0MHz)

| Symbol | Parameter | Conditions ⁽²⁾ | Max. | Unit |
|---------------------|--------------------|---------------------------|------|------|
| CIN | Input Capacitance | VIN = 3dV | 9 | pF |
| COUT ⁽³⁾ | Output Capacitance | VOUT = 3dV | 10 | pF |

NOTES:

- These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- COUT also references CIO.

4859 tbl 07

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

| Symbol | Parameter | Test Conditions | 70V9199/099L | | Unit |
|--------|--------------------------------------|--|--------------|------|------|
| | | | Min. | Max. | |
| ILI | Input Leakage Current ⁽¹⁾ | VDD = 3.6V, VIN = 0V to VDD | — | 5 | μA |
| ILO | Output Leakage Current | $\overline{CE} = V_{IH}$ or $CE_1 = V_{IL}$, VOUT = 0V to VDD | — | 5 | μA |
| VOL | Output Low Voltage | IOL = +4mA | — | 0.4 | V |
| VOH | Output High Voltage | Ioh = -4mA | 2.4 | — | V |

NOTE:

- At VDD ≤ 2.0V input leakages are undefined.

4859 tbl 08

DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range⁽³⁾ ($V_{DD} = 3.3V \pm 0.3V$)

| Symbol | Parameter | Test Condition | Version | 70V9199/099L9 Com'l & Ind | | 70V9199/099L12 Com'l Only | | Unit |
|--------|---|---|---------|------------------------------|------|------------------------------|------|------|
| | | | | Typ. ⁽⁴⁾ | Max. | Typ. ⁽⁴⁾ | Max. | |
| IDD | Dynamic Operating Current (Both Ports Active) | \overline{CE}_L and $\overline{CE}_R = V_{IL}$, Outputs Disabled, $f = f_{MAX}^{(1)}$ | COM'L L | 175 | 230 | 150 | 200 | mA |
| | | | IND L | 180 | 240 | — | — | |
| ISB1 | Standby Current (Both Ports - TTL Level Inputs) | $\overline{CE}_L = \overline{CE}_R = V_{IH}$ $f = f_{MAX}^{(1)}$ | COM'L L | 40 | 65 | 30 | 50 | mA |
| | | | IND L | 50 | 70 | — | — | |
| ISB2 | Standby Current (One Port - TTL Level Inputs) | $\overline{CE}^*A = V_{IL}$ and $\overline{CE}^*B = V_{IH}^{(5)}$ Active Port Outputs Disabled, $f = f_{MAX}^{(1)}$ | COM'L L | 110 | 145 | 95 | 130 | mA |
| | | | IND L | 110 | 155 | — | — | |
| ISB3 | Full Standby Current (Both Ports - CMOS Level Inputs) | Both Ports \overline{CE}_L and $\overline{CE}_R \geq V_{DD} - 0.2V$, $V_{IN} \geq V_{DD} - 0.2V$ or $V_{IN} \leq 0.2V$, $f = 0^{(2)}$ | COM'L L | 0.4 | 2 | 0.4 | 2 | mA |
| | | | IND L | 0.4 | 2 | — | — | |
| ISB4 | Full Standby Current (One Port - CMOS Level Inputs) | $\overline{CE}^*A \leq 0.2V$ and $\overline{CE}^*B \geq V_{DD} - 0.2V^{(5)}$ $V_{IN} \geq V_{DD} - 0.2V$ or $V_{IN} \leq 0.2V$, Active Port, Outputs Disabled, $f = f_{MAX}^{(1)}$ | COM'L L | 100 | 140 | 90 | 125 | mA |
| | | | IND L | 100 | 155 | — | — | |

4859 tbl 09

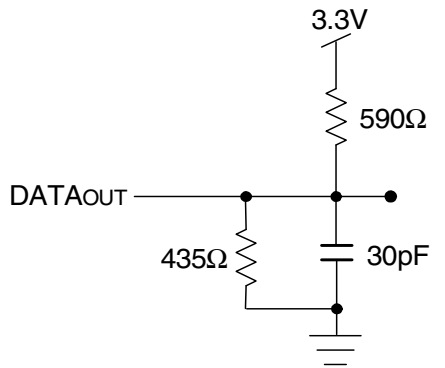
NOTES:

- At $f = f_{MAX}$, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of $1/t_{cvc}$, using "AC TEST CONDITIONS" at input levels of GND to 3V.
- $f = 0$ means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- $V_{DD} = 3.3V$, $T_A = 25^\circ C$ for Typ, and are not production tested. $I_{DD} dc(f=0) = 90mA$ (Typ).
- $\overline{CE}_X = V_{IL}$ means $\overline{CE}_{0X} = V_{IL}$ and $CE_{1X} = V_{IH}$
 $\overline{CE}_X = V_{IH}$ means $\overline{CE}_{0X} = V_{IH}$ or $CE_{1X} = V_{IL}$
 $\overline{CE}_X \leq 0.2V$ means $\overline{CE}_{0X} \leq 0.2V$ and $CE_{1X} \geq V_{DD} - 0.2V$
 $\overline{CE}_X \geq V_{DD} - 0.2V$ means $\overline{CE}_{0X} \geq V_{DD} - 0.2V$ or $CE_{1X} \leq 0.2V$
 "X" represents "L" for left port or "R" for right port.

AC Test Conditions

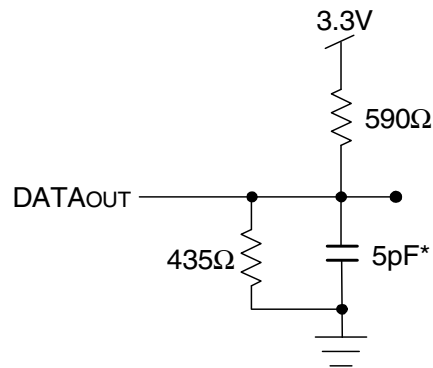
| | |
|-------------------------------|---------------------|
| Input Pulse Levels | GND to 3.0V |
| Input Rise/Fall Times | 3ns Max. |
| Input Timing Reference Levels | 1.5V |
| Output Reference Levels | 1.5V |
| Output Load | Figures 1, 2, and 3 |

4859 tbl 10



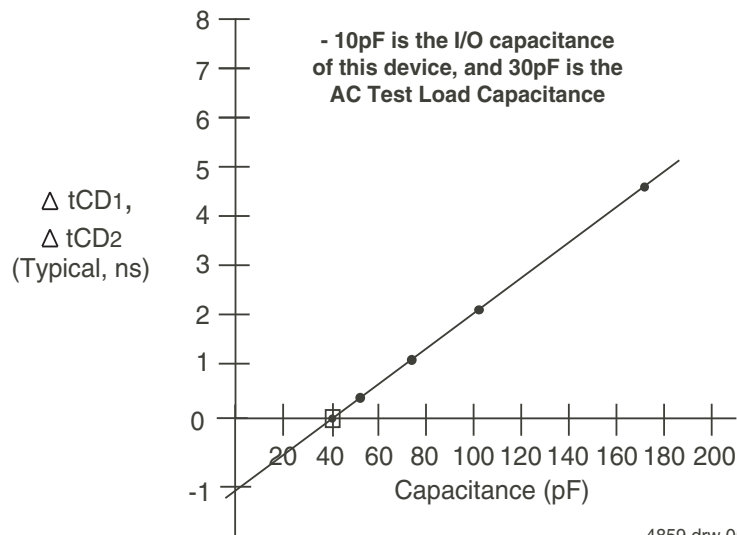
4859 drw 03

Figure 1. AC Output Test load.



4859 drw 04

Figure 2. Output Test Load
(For t_{CKLZ} , t_{CKHZ} , t_{OLZ} , and t_{OHZ}).
*Including scope and jig.



4859 drw 05

Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)⁽³⁾ ($V_{DD} = 3.3V \pm 0.3V$)

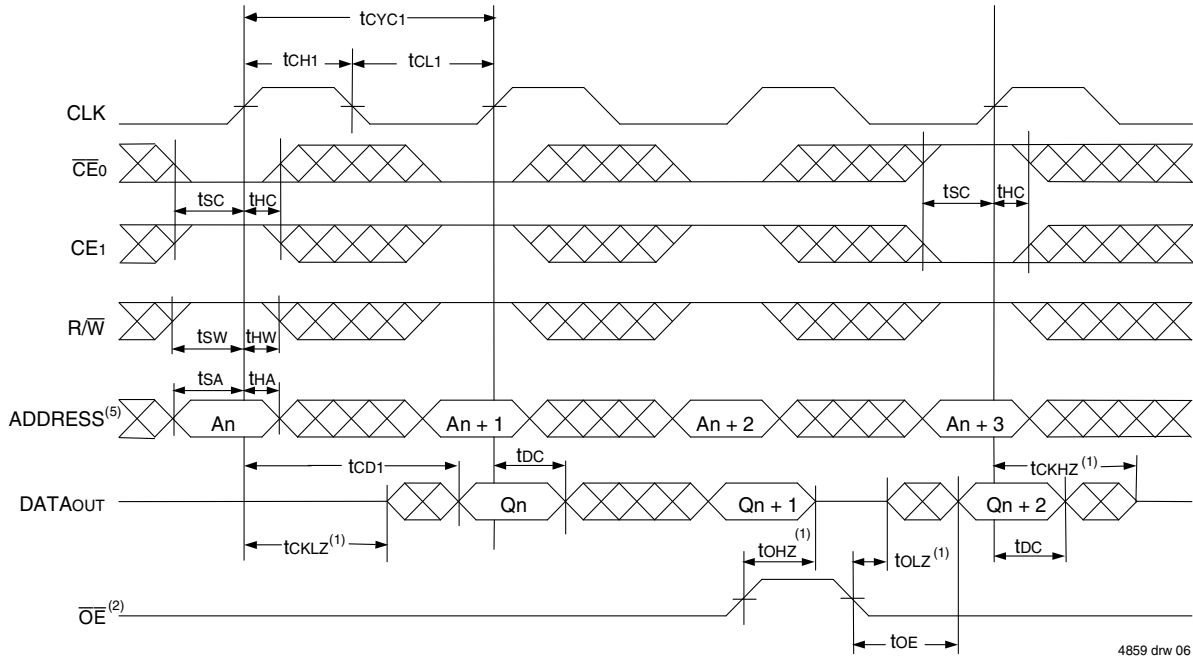
| Symbol | Parameter | 70V9199/099L9 Com'l & Ind | | 70V9199/099L12 Com'l Only | | Unit |
|---------------------------|---|------------------------------|------|------------------------------|------|------|
| | | Min. | Max. | Min. | Max. | |
| t _{CYC1} | Clock Cycle Time (Flow-Through) ⁽²⁾ | 25 | — | 30 | — | ns |
| t _{CYC2} | Clock Cycle Time (Pipelined) ⁽²⁾ | 15 | — | 20 | — | ns |
| t _{CH1} | Clock High Time (Flow-Through) ⁽²⁾ | 12 | — | 12 | — | ns |
| t _{CL1} | Clock Low Time (Flow-Through) ⁽²⁾ | 12 | — | 12 | — | ns |
| t _{CH2} | Clock High Time (Pipelined) ⁽²⁾ | 6 | — | 8 | — | ns |
| t _{CL2} | Clock Low Time (Pipelined) ⁽²⁾ | 6 | — | 8 | — | ns |
| t _R | Clock Rise Time | — | 3 | — | 3 | ns |
| t _F | Clock Fall Time | — | 3 | — | 3 | ns |
| t _{SA} | Address Setup Time | 4 | — | 4 | — | ns |
| t _{HA} | Address Hold Time | 1 | — | 1 | — | ns |
| t _{SC} | Chip Enable Setup Time | 4 | — | 4 | — | ns |
| t _{HC} | Chip Enable Hold Time | 1 | — | 1 | — | ns |
| t _{SW} | R/W Setup Time | 4 | — | 4 | — | ns |
| t _{HW} | R/W Hold Time | 1 | — | 1 | — | ns |
| t _{SD} | Input Data Setup Time | 4 | — | 4 | — | ns |
| t _{HD} | Input Data Hold Time | 1 | — | 1 | — | ns |
| t _{SAD} | \overline{ADS} Setup Time | 4 | — | 4 | — | ns |
| t _{HAD} | \overline{ADS} Hold Time | 1 | — | 1 | — | ns |
| t _{SCN} | \overline{CNTEN} Setup Time | 4 | — | 4 | — | ns |
| t _{HCN} | \overline{CNTEN} Hold Time | 1 | — | 1 | — | ns |
| t _{SRST} | \overline{CNTRST} Setup Time | 4 | — | 4 | — | ns |
| t _{HRST} | \overline{CNTRST} Hold Time | 1 | — | 1 | — | ns |
| t _{OE} | Output Enable to Data Valid | — | 9 | — | 12 | ns |
| t _{OLZ} | Output Enable to Output Low-Z ⁽¹⁾ | 2 | — | 2 | — | ns |
| t _{OHZ} | Output Enable to Output High-Z ⁽¹⁾ | 1 | 7 | 1 | 7 | ns |
| t _{CD1} | Clock to Data Valid (Flow-Through) ⁽²⁾ | — | 20 | — | 25 | ns |
| t _{CD2} | Clock to Data Valid (Pipelined) ⁽²⁾ | — | 9 | — | 12 | ns |
| t _{DC} | Data Output Hold After Clock High | 2 | — | 2 | — | ns |
| t _{CKHZ} | Clock High to Output High-Z ⁽¹⁾ | 2 | 9 | 2 | 9 | ns |
| t _{CKLZ} | Clock High to Output Low-Z ⁽¹⁾ | 2 | — | 2 | — | ns |
| Port-to-Port Delay | | | | | | |
| t _{CWDD} | Write Port Clock High to Read Data Delay | — | 35 | — | 40 | ns |
| t _{CCS} | Clock-to-Clock Setup Time | — | 15 | — | 15 | ns |

4859 tbl 11

NOTES:

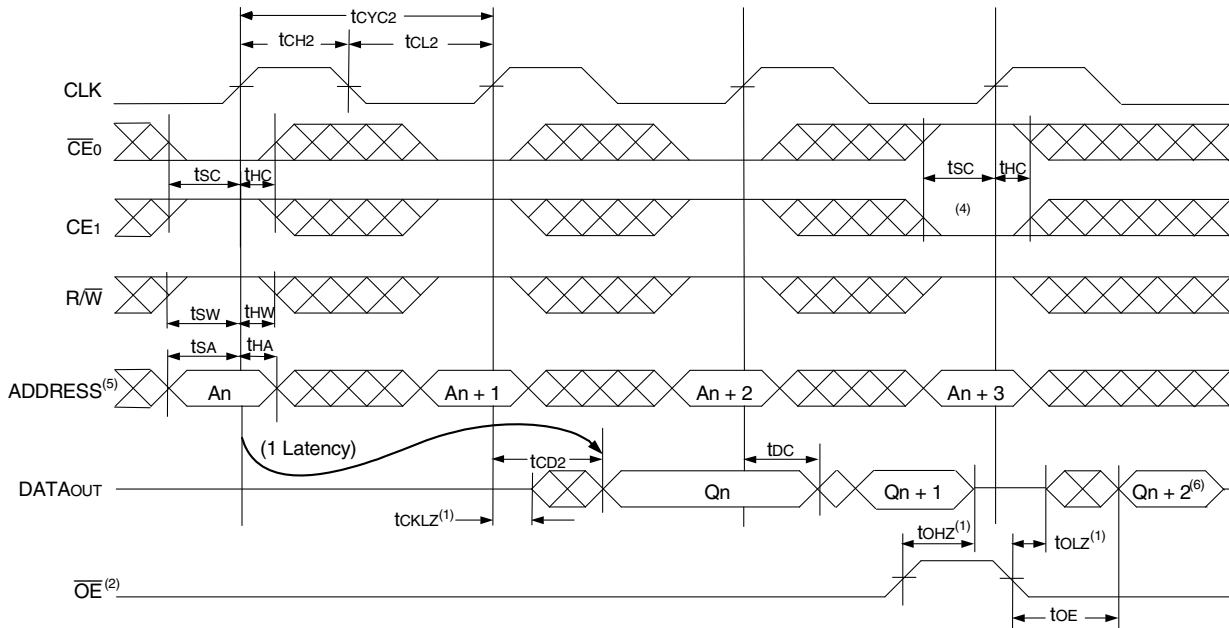
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.
2. The Pipelined output parameters (t_{CYC2}, t_{CD2}) apply to either or both the Left and Right ports when $\overline{FT}/PIPE = V_{IH}$. Flow-through parameters (t_{CYC1}, t_{CD1}) apply when $\overline{FT}/PIPE = V_{IL}$ for that port.
3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (\overline{OE}), $\overline{FT}/PIPE_R$, and $\overline{FT}/PIPE_L$.

Timing Waveform of Read Cycle for Flow-Through Output ($\overline{\text{FT}}/\text{PIPE} \text{ "X" } = V_{\text{IL}}$)^(3,6)



4859 drw 06

Timing Waveform of Read Cycle for Pipelined Operation ($\overline{\text{FT}}/\text{PIPE} \text{ "X" } = V_{\text{IH}}$)^(3,6)

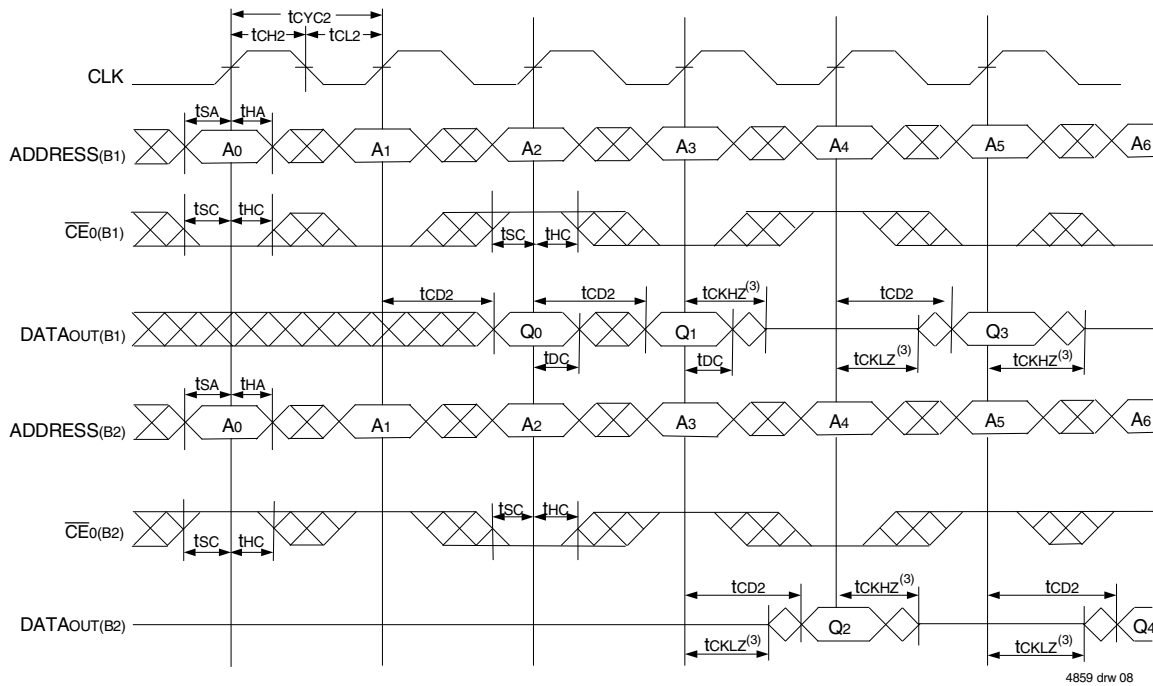


4859 drw 07

NOTES:

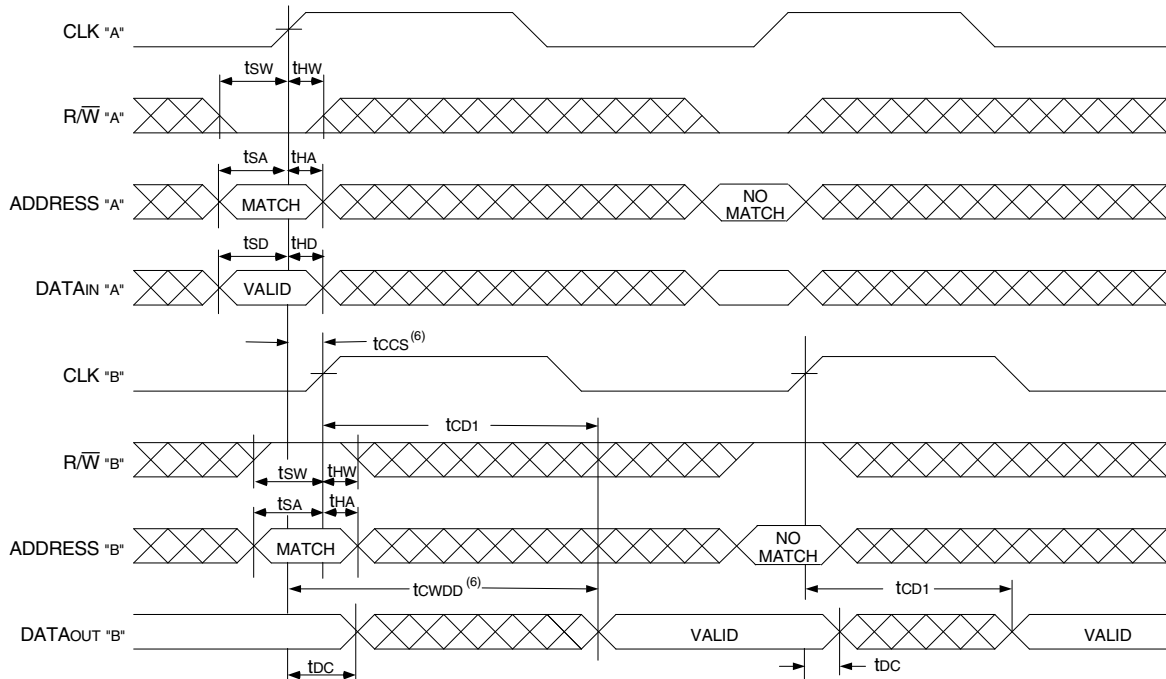
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
2. $\overline{\text{OE}}$ is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
3. $\text{ADS} = V_{\text{IL}}$ and $\text{CNTRST} = V_{\text{IH}}$.
4. The output is disabled (High-Impedance state) by $\overline{\text{CE}}_0 = V_{\text{IH}}$ or $\text{CE}_1 = V_{\text{IL}}$ following the next rising edge of the clock. Refer to Truth Table 1.
5. Addresses do not have to be accessed sequentially since $\text{ADS} = V_{\text{IL}}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
6. 'X' here denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Bank Select Pipelined Read^(1,2)



4859 drw 08

Timing Waveform with Port-to-Port Flow-Through Read^(4,5,7)

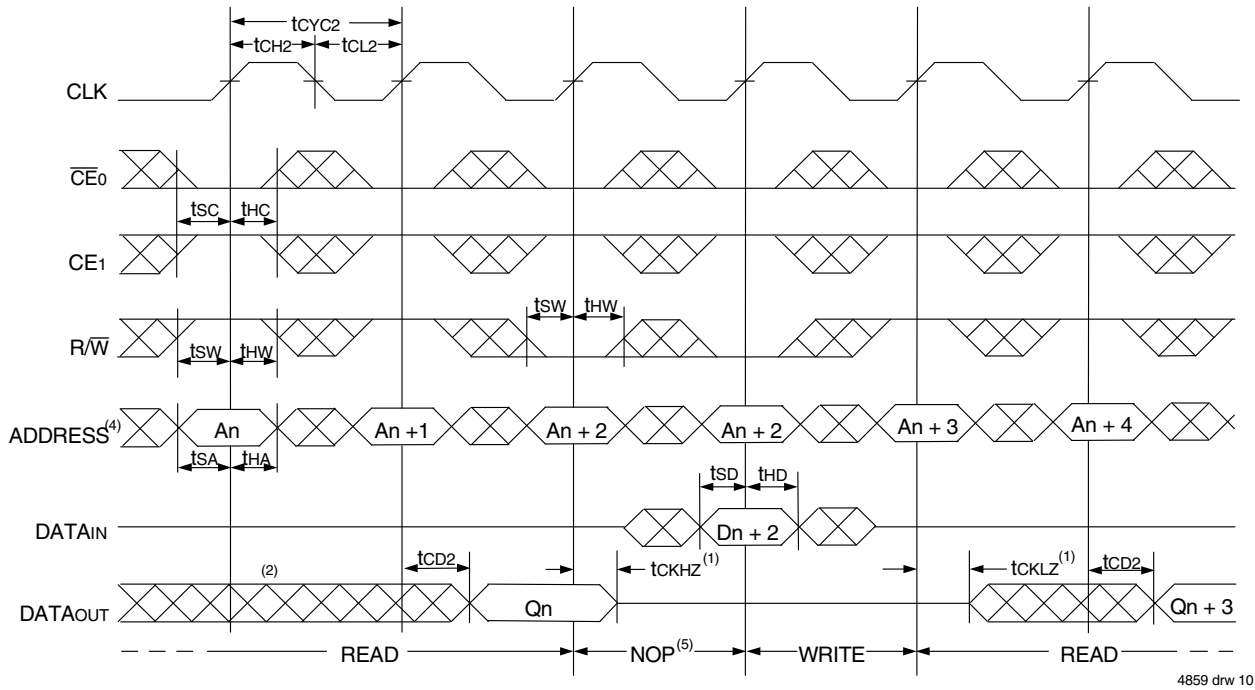


4859 drw 09

NOTES:

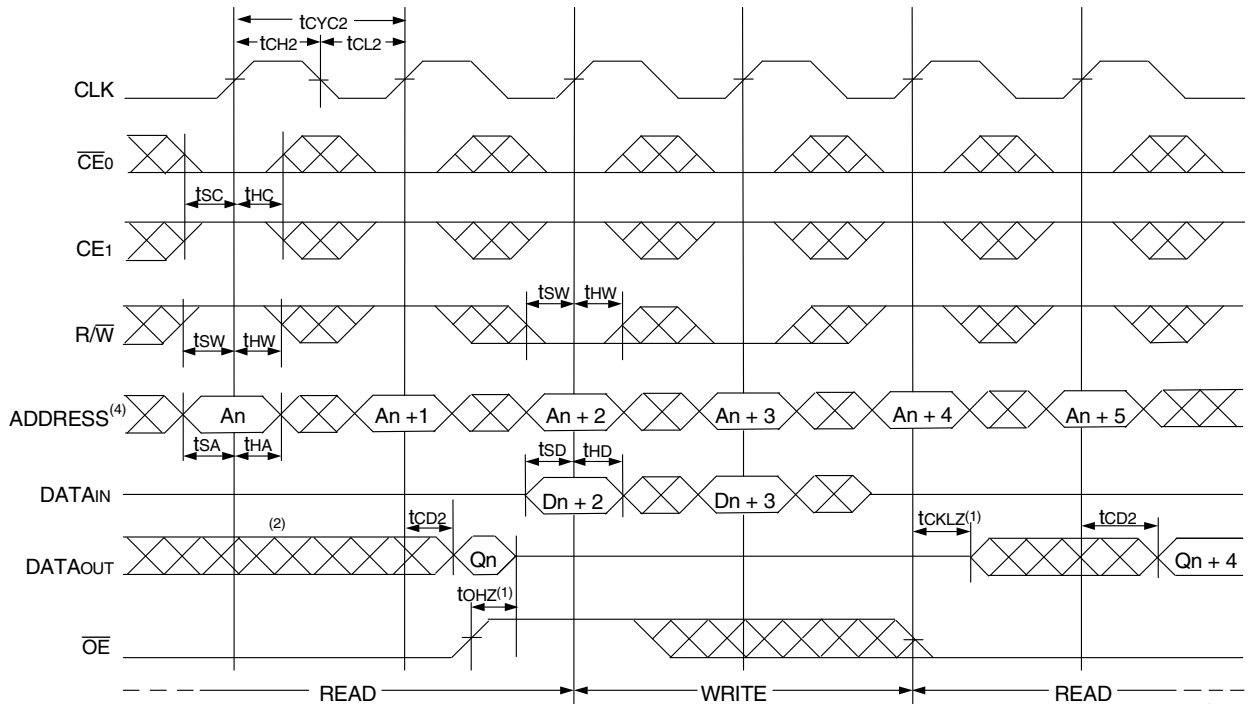
1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9199/099 for this waveform, and are setup for depth expansion in this example. ADDRESS_(B1) = ADDRESS_(B2) in this situation.
2. \overline{OE} and $\overline{ADS} = V_{IL}$; CE_{1(B1)}, CE_{1(B2)}, R/W and $\overline{CNTRST} = V_{IH}$.
3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
4. \overline{CE}_0 and $\overline{ADS} = V_{IL}$; CE₁ and $\overline{CNTRST} = V_{IH}$.
5. $\overline{OE} = V_{IL}$ for the Right Port, which is being read from. $\overline{OE} = V_{IH}$ for the Left Port, which is being written to.
6. If $t_{CCS} \leq$ maximum specified, then data from right port READ is not valid until the maximum specified for t_{CWD} . If $t_{CCS} >$ maximum specified, then data from right port READ is not valid until $t_{CCS} + t_{CD1}$. t_{CWD} does not apply in this case.
7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".

Timing Waveform of Pipelined Read-to-Write-to-Read ($\overline{OE} = V_{IL}$)⁽³⁾



4859 drw 10

Timing Waveform of Pipelined Read-to-Write-to-Read (\overline{OE} Controlled)⁽³⁾

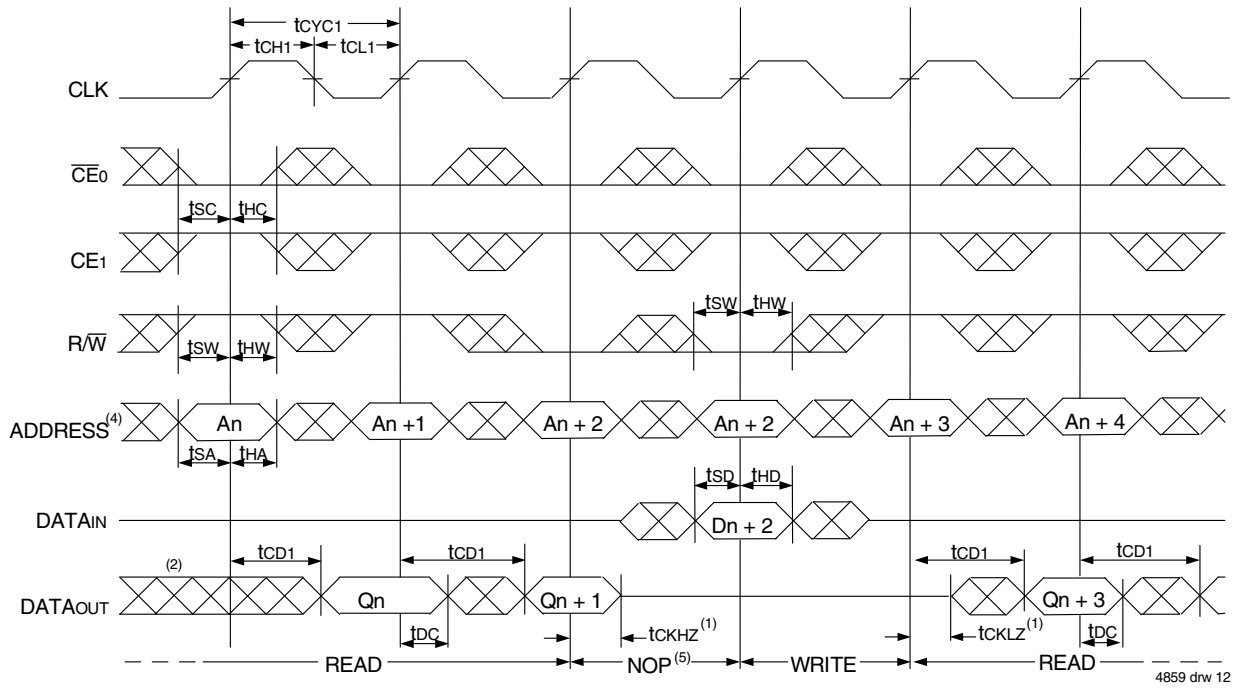


4859 drw 11

NOTES:

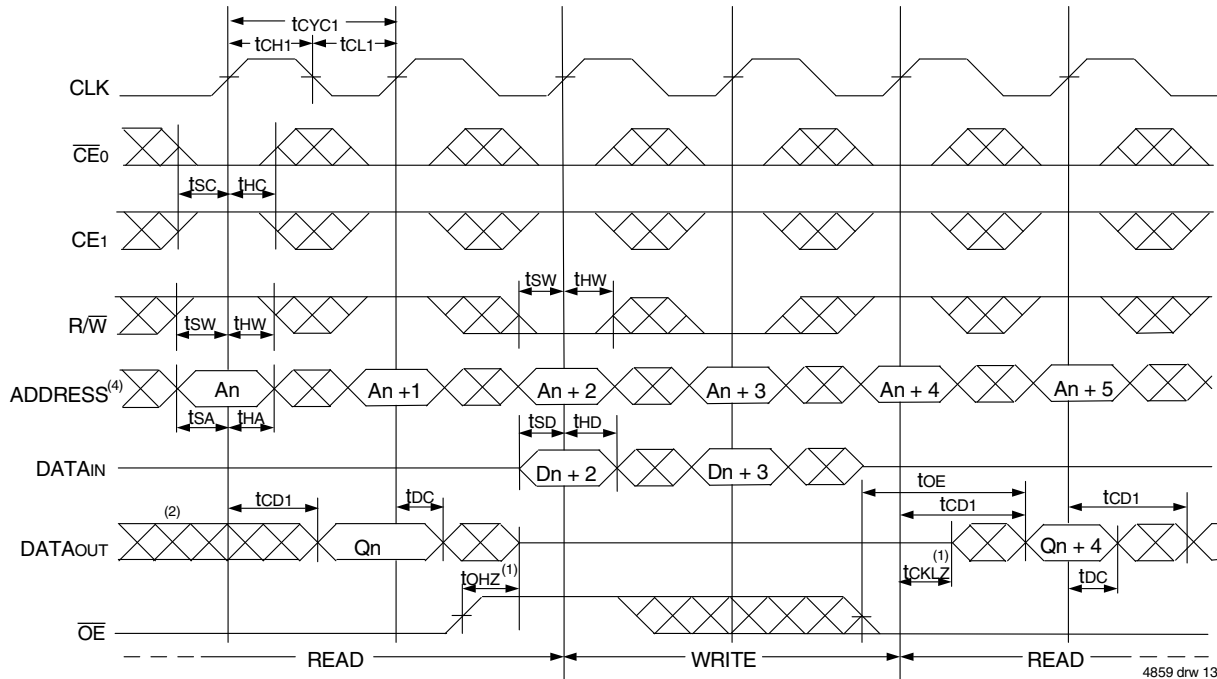
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
3. \overline{CE}_0 and $\overline{ADS} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$. "NOP" is "No Operation".
4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.

Timing Waveform of Flow-Through Read-to-Write-to-Read ($\overline{OE} = V_{IL}$)⁽³⁾



4859 drw 12

Timing Waveform of Flow-Through Read-to-Write-to-Read (\overline{OE} Controlled)⁽³⁾

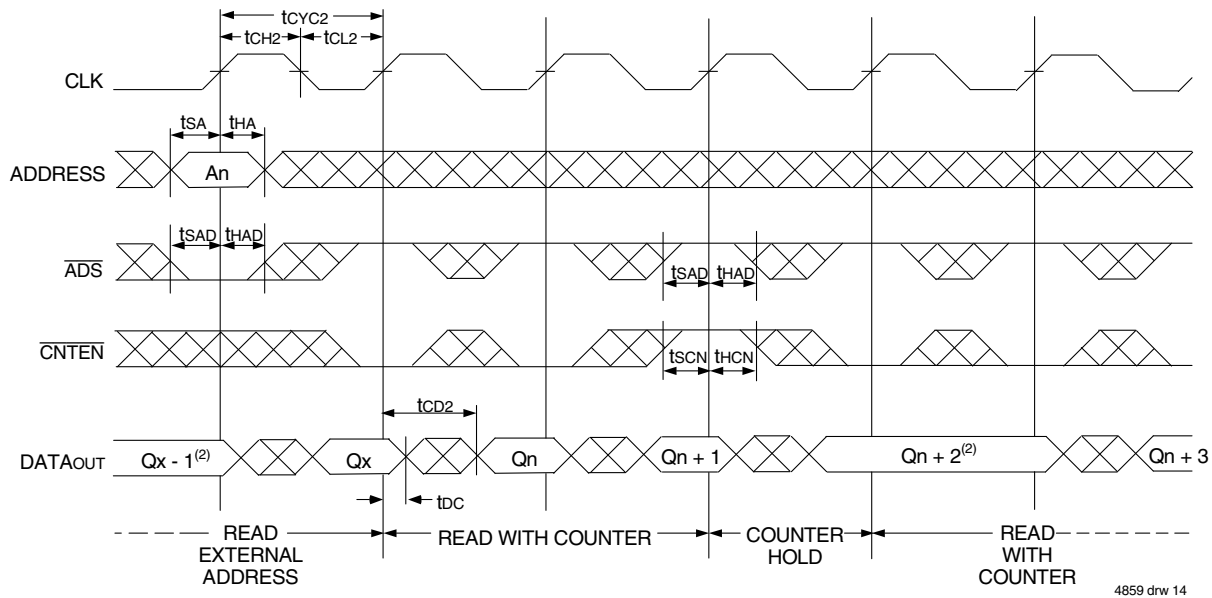


4859 drw 13

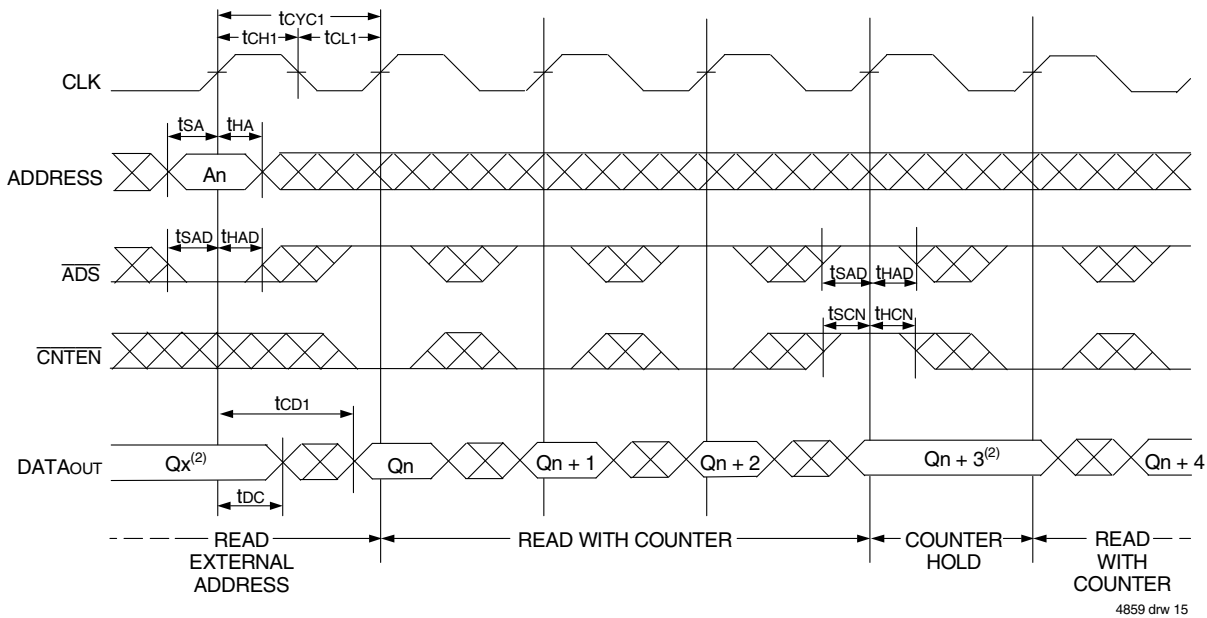
NOTES:

1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
3. $\overline{CE0}$ and $\overline{ADS} = V_{IL}$; $CE1$ and $\overline{CNTRST} = V_{IH}$. "NOP" is "No Operation".
4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾



Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾

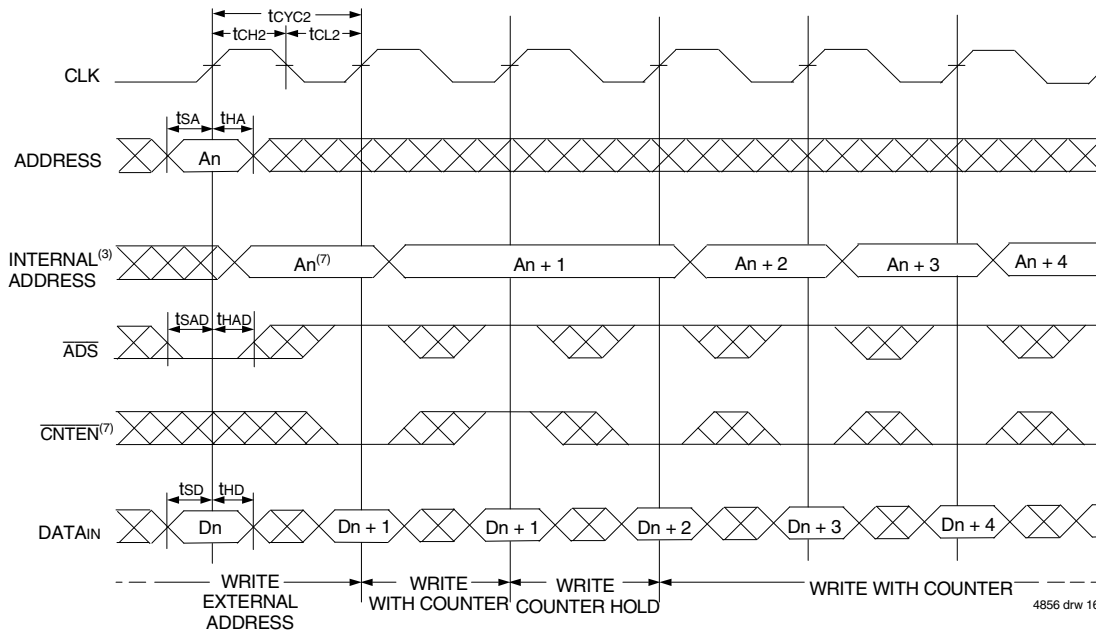


NOTES:

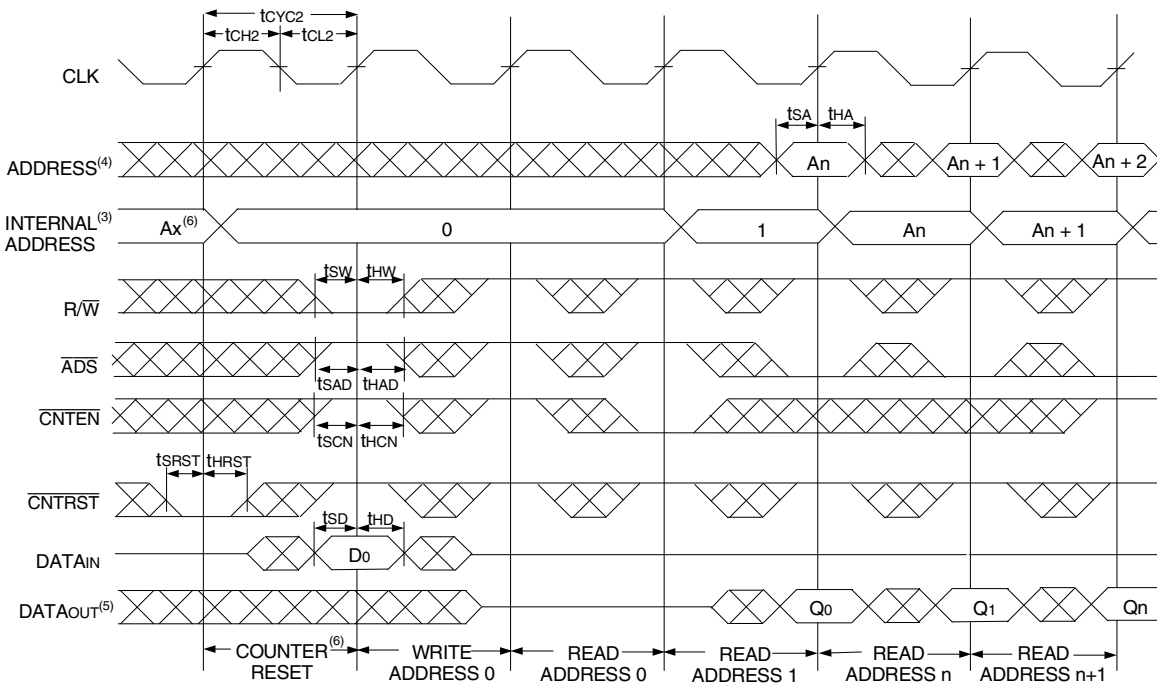
1. \overline{CE}_0 and $\overline{OE} = V_{IL}$; CE_1 , $R\overline{W}$, and $\overline{CNRST} = V_{IH}$.

2. If there is no address change via $\overline{ADS} = V_{IL}$ (loading a new address) or $\overline{CNTEN} = V_{IL}$ (advancing the address), i.e. $\overline{ADS} = V_{IH}$ and $\overline{CNTEN} = V_{IH}$, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)⁽²⁾



NOTES:

1. \overline{CE}_0 and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$.
2. $\overline{CE}_0 = V_{IL}$; $CE_1 = V_{IH}$.
3. The "Internal Address" is equal to the "External Address" when $\overline{ADS} = V_{IL}$ and equals the counter output when $\overline{ADS} = V_{IH}$.
4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDR₀ will be accessed. Extra cycles are shown here simply for clarification.
7. $\overline{CNTEN} = V_{IL}$ advances Internal Address from 'An' to 'An + 1'. The transition shown indicates the time required for the counter to advance. The 'An + 1' Address is written during this cycle.

Functional Description

The IDT70V9199/099 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to staff the operation of the address counters for fast interleaved memory applications.

$\overline{CE_0} = V_{IL}$ and $CE_1 = V_{IH}$ for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9199/099's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with $\overline{CE_0} = V_{IH}$ or $CE_1 = V_{IL}$ to reactivate the outputs.

Depth and Width Expansion

The IDT70V9199/099 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT70V9199/099 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 18/16-bit or wider applications.

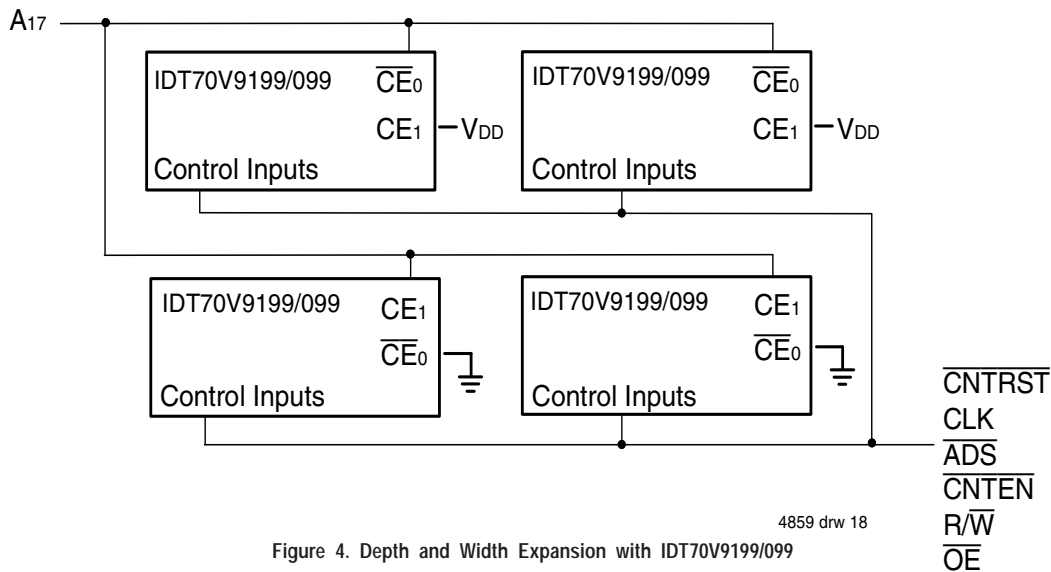
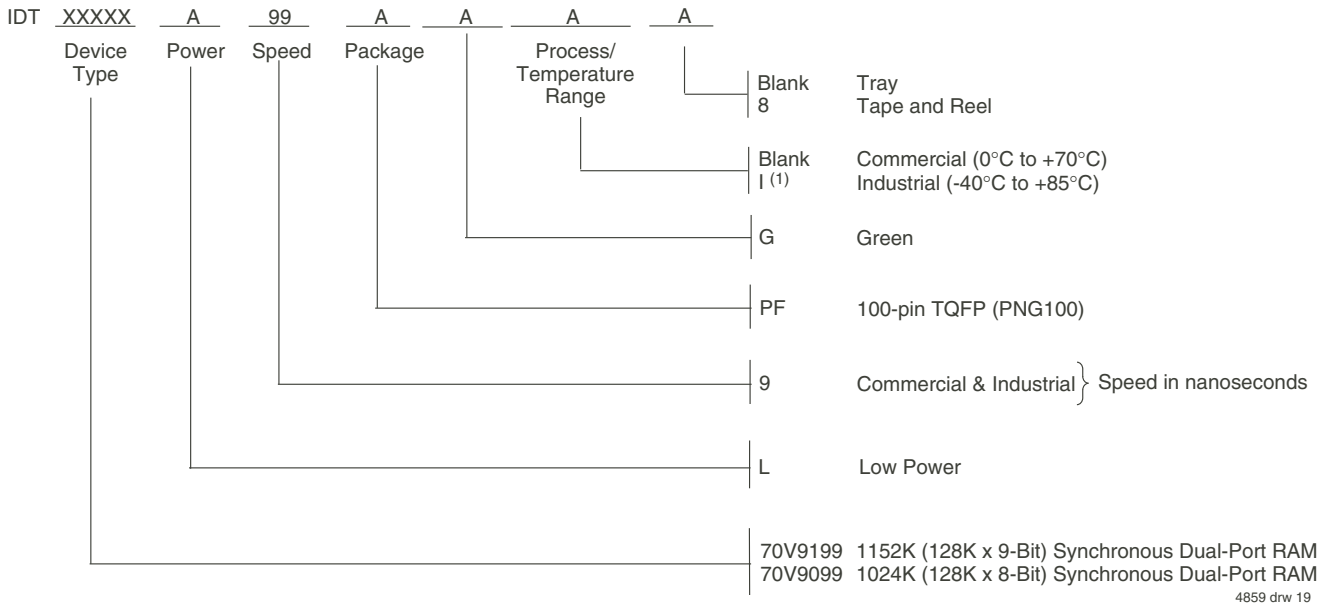


Figure 4. Depth and Width Expansion with IDT70V9199/099

Ordering Information



NOTES:

- Industrial temperature range is available. For specific speeds, packages and powers contact your sales office.
LEAD FINISH (SnPb) parts are Obsolete. Product Discontinuation Notice - PDN# SP-17-02
 Note that information regarding recently obsoleted parts are included in this datasheet for customer convenience.

IDT Clock Solution for IDT70V9199/099 Dual-Port

| IDT Dual-Port Part Number | Dual-Port I/O Specifications | | Dual-Port Clock Specifications | | | | IDT PLL Clock Devices | IDT Non-PLL Clock Devices |
|---------------------------|------------------------------|-------|--------------------------------|------------------------------|-------------------|------------------|-------------------------------|--|
| | Voltage | I/O | Input Capacitance | Input Duty Cycle Requirement | Maximum Frequency | Jitter Tolerance | | |
| 70V9199/099 | 3.3 | LVTTL | 9pF | 40% | 100 | 150ps | IDT2305 IDT2308 IDT2309 | FCT3805 FCT3805D/E FCT3807 FCT3807D/E |

4859 tbl12

Orderable Part Information

| Speed (ns) | Orderable Part ID | Pkg. Code | Pkg. Type | Temp. Grade |
|------------|-------------------|-----------|-----------|-------------|
| 9 | 70V9199L9PFGI | PNG100 | TQFP | I |
| | 70V9199L9PFGI8 | PNG100 | TQFP | I |

| Speed (ns) | Orderable Part ID | Pkg. Code | Pkg. Type | Temp. Grade |
|------------|-------------------|-----------|-----------|-------------|
| 9 | 70V9099L9PFG | PNG100 | TQFP | C |
| | 70V9099L9PFG8 | PNG100 | TQFP | C |

Datasheet Document History

| | | |
|-----------|-----------------|---|
| 09/30/99: | | Initial Public Release |
| 11/12/99: | | Replaced IDT logo |
| 01/10/01: | Page 3 | Changed information in Truth Table II |
| | Page 4 | Increased storage temperature parameters |
| | | Clarified TA parameter |
| | Page 5 | DC Electrical parameters–changed wording from "open" to "disabled" |
| | | Changed $\pm 200\text{mV}$ to 0mV in notes |
| | | Removed Preliminary status |
| 04/09/03: | | Consolidate multiple devices into one datasheet |
| | | Changed naming conventions from V_{CC} to V_{DD} and from GND to V_{SS} |
| | Pages 2 & 3 | Added date revision to pin configurations |
| | Page 5 | Added junction temperature to Absolute Maximum Ratings Table |
| | | Added Ambient Temperature footnote |
| | Pages 1, 6 & 16 | Added 6ns speed grade |
| | Page 6 | Added updated DC power numbers to the DC Electrical Characteristics Table |
| | Page 8 | Added 6ns speed AC timing numbers and changed t_{OE} to be equal to t_{CD2} in the AC Electrical Characteristics Table |
| | Page 16 | Added IDT Clock Solution Table |
| 01/10/06: | Page 1 | Added green availability to features |
| | Page 16 | Added green indicator to ordering information |
| 02/22/07: | Page 1 | Removed 6ns & 7ns speed grades from features |
| | Page 6 | Removed 6ns & 7ns speed grade values from the DC Electrical Characteristics Table |
| | Page 8 | Removed 6ns & 7ns speed grade values from the AC Electrical Characteristics Table |
| | Page 16 | Removed 6ns & 7ns speed grades from ordering information |
| 01/19/09: | Page 16 | Removed "IDT" from orderable part number |
| 07/26/10: | Page 8 | In order to correct the header notes of the AC Elect Chars Table and align them with the Industrial temp range values located in the table, the commercial TA header note has been removed |
| | Pages 9-12 | In order to correct the footnotes of timing diagrams, \overline{CNTEN} has been removed to reconcile the footnotes with the \overline{CNTEN} logic definition found in Truth Table II - Address Counter Control |
| 03/01/18: | | Product Discontinuation Notice - PDN# SP-17-02 |
| | | Last time buy expires June 15, 2018 |
| 07/25/19: | Page 1 & 16 | Deleted obsolete Commercial speed grade 12ns in Features and Ordering Information |
| | Page 2 & 3 | Rotated PNG100 TQFP pin configurations to accurately reflect pin 1 orientation |
| | Page 2 & 3 | Updated package code PN100-1 to PNG100 |
| | Page 16 | Added Orderable Part Information |

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